

12th Global Symposium on Millimeter Waves 2019 (GSMM 2019)

May 22-24, 2019, Tohoku University, Sendai, Japan

First Call for Papers

The main theme of the GSMM2019 is Millimeter-wave Propagation: Hardware, Measurements and Systems. It covers millimeter-wave and THz devices, circuits, systems, and applications. The conference will include keynote talks, technical sessions and poster sessions on the listed topics. This conference will be sponsored by Research Institute of Electrical Communication (RIEC), Tohoku University and technically sponsored by IEEE MTT-S, IEEE MTT-S Japan Chapter, IEEE AP-S Tokyo Chapter, and Technical Committee on Microwaves / Technical Committee on Radio Communication Systems of IEICE. As you may know, Sendai is one of the historic sites for microwave & antenna engineering and is the birthplace of Yagi-Uda antenna. Please enjoy the atmosphere of Sendai.

Topics

The topics include, but are not limited to, the following technical areas:

- ❑ **Millimeter-Wave Antennas and Passive Devices:** Antennas and Propagation; Waveguides and Transmission Lines; Filters; Multiple-Element Antenna Arrays; Materials, Substrates, and Packaging
- ❑ **Millimeter-Wave and THz Communications:** 5G Wireless Communications; Wireless Channel Measurements and Modeling; Over-the-Air (OTA) Test Methods; Wireless LANs and PANs; Backhaul for 4G/5G Small Cells; Satellite Communications
- ❑ **Millimeter-Wave and THz Sensing:** Instruments for Radio Astronomy; Radar, Remote Sensing, and Imaging; Systems and Subsystems;
- ❑ **Sub-Millimeter-Wave and THz Technologies:** Devices and Systems; Photonic Devices and Systems; Integration Technologies
- ❑ **Millimeter-Wave Active Devices and ICs:** Devices: MMICs, PAs, LNAs, Mixers, Multipliers, VCOs Technologies: HEMT, CMOS, HBT, GaN, SiGe, Schottky, HBV On-Wafer and Advanced Measurements
- ❑ **Emerging Technologies and Applications:** Internet-of-Things (IoT) and Machine-to-Machine (M2M); Biomedical Applications; Wireless Power Transfer (WPT); Nano-Electronic Devices; Automotive and Industrial Applications; New Materials

Paper submission: Jan. 28, 2019

Notification of Acceptance: Feb. 25, 2019

Final Paper Submission: Mar. 18, 2019

Preparation of Papers

All submitted papers will be reviewed by the technical program committee of the conference and accepted papers that are found to be consistent with the required content and format will be submitted to IEEE Xplore. Detailed submission guidelines can be found at the conference website

<http://www.wit.riec.tohoku.ac.jp/GSMM2019>

Sendai City



Sendai is one of the largest cities in Japan, and is the political and economic center in the Tohoku (northeast) region. It is also well known as the City of Trees, where the Japanese Zelkova trees on the streets are in harmony with the View of the modern city.

Shinkansen Train (1hr 30min. from Tokyo Station)
Int. flights from major East Asian cities.
Connecting flights from Narita (NRT), Nagoya (NGO), Fukuoka (FUK).

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